

IN THE SPECIFICATION:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 10/211,021, filed August 2, 2002, ~~pending~~ now U.S. Patent 6,700,206, issued March 3, 2004.

Please replace paragraph number [0031] with the following rewritten paragraph:

[0031] The semiconductor device package 10 includes a lead frame 12 which, other than a few modifications which shall be set forth in greater detail below, includes a conventional chip-on-leads (COL)-type lead frame configured with a centrally located die paddle ~~12~~ 14 and a plurality of lead fingers 16 peripherally located relative to the die paddle 14. The lead frame ~~14~~ 12 may be made from materials and by processes known to those of ordinary skill in the art. For example, copper and copper alloys are suitable materials, and may be stamped or etched from sheet form to define strips of lead frames.

Please replace paragraph number [0046] with the following rewritten paragraph:

[0046] Further, it is noted that the tie bars 54 of the lead frame 12 are desirably located in what may be termed "stay out zones," meaning that the tie bars 54 are strategically located so that they do not interfere with the wire bonds 24 or other electrical connections extending between the bond pads ~~24~~ 22 and the lead fingers 16. Thus, as seen in FIG. 3, the tie bars 54 extend substantially diagonally outwardly from corners of the die paddle 14 so that they do not cover or otherwise conceal the bond pads ~~24~~ 22 of the first semiconductor die 18. Aside from supporting the die paddle 14 prior to excise and trim of the lead frame 12, the tie bars 54 also serve to transfer heat from the die paddle 14 to the external periphery of the dielectric material 40 (not shown in FIGS. 3-5).